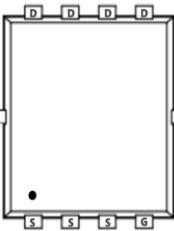
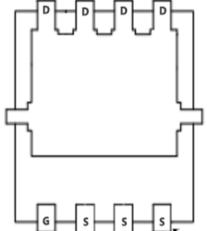
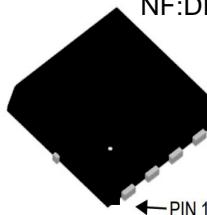
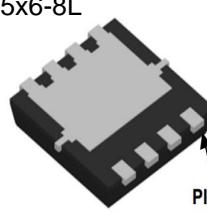
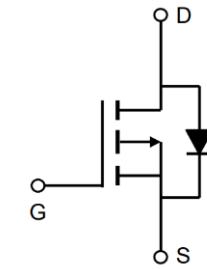


**TM006P03NF**
**P-Channel Enhancement Mosfet**

<b>General Description</b> <ul style="list-style-type: none"> <li>• Low <math>R_{DS(ON)}</math></li> <li>• RoHS and Halogen-Free Compliant</li> </ul> <b>Applications</b> <ul style="list-style-type: none"> <li>• Load switch</li> <li>• PWM</li> </ul>	<b>General Features</b> <p><math>V_{DS} = -30V</math> <math>I_D = -70A</math></p> <p><math>R_{DS(ON)} = 6m\Omega</math>(typ.) @ <math>V_{GS} = -10V</math></p> <p>100% UIS Tested 100% <math>R_g</math> Tested</p> 
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Marking: 70P03F

<b>Absolute Maximum Ratings</b> ( $T_A = 25^\circ C$ Unless Otherwise Noted)				
Parameter	Symbol	Value	Unit	
Drain-Source Voltage	$V_{DS}$	-30	V	
Gate-Source Voltage	$V_{GS}$	$\pm 20$	V	
Continuous Drain Current@-10V <sup>1</sup>	$I_D$	-70	A	
		-40		
Pulsed Drain Current <sup>2</sup>	$I_{DM}$	-175	A	
Single Pulse Avalanche Energy <sup>3</sup>	$E_{AS}$	31	mJ	
Avalanche Current	$I_{AS}$	-70	A	
Total Power Dissipation <sup>4</sup>	$P_D$	31.2	W	
Operating Junction and Storage Temperature Range	$T_J, T_{STG}$	-55 to +150	°C	

<b>Thermal Characteristics</b>				
Parameter	Symbol	Value	Unit	
Thermal Resistance from Junction-to-Ambient <sup>1</sup>	$R_{\theta JA}$	61	°C/W	
Thermal Resistance from Junction-to-Case <sup>1</sup>	$R_{\theta JC}$	4	°C/W	

**Electrical Characteristics**  $T_c = 25^\circ\text{C}$ , unless otherwise noted

Parameter	Symbol	Test Conditions	Min.	Typ.	Max.	Unit
<b>Static Characteristics</b>						
Drain-Source Breakdown Voltage	$V_{(\text{BR})\text{DSS}}$	$V_{\text{GS}} = 0\text{V}, I_D = -250\mu\text{A}$	-30	-	-	V
Gate-body Leakage current	$I_{\text{GSS}}$	$V_{\text{DS}} = 0\text{V}, V_{\text{GS}} = \pm 20\text{V}$	-	-	$\pm 100$	nA
Zero Gate Voltage Drain Current $T_J=25^\circ\text{C}$	$I_{\text{DSS}}$	$V_{\text{DS}} = -24\text{V}, V_{\text{GS}} = 0\text{V}$	-	-	-1	$\mu\text{A}$
$T_J=55^\circ\text{C}$			-	-	-5	
Gate-Threshold Voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{DS}} = V_{\text{GS}}, I_D = -250\mu\text{A}$	-1.0	-1.6	-2.5	V
Drain-Source On-Resistance <sup>2</sup>	$R_{\text{DS}(\text{on})}$	$V_{\text{GS}} = -10\text{V}, I_D = -12\text{A}$	-	6	8.8	$\text{m}\Omega$
		$V_{\text{GS}} = -4.5\text{V}, I_D = -8\text{A}$	-	9	14	
Forward Transconductance	$g_{\text{fs}}$	$V_{\text{DS}} = -5\text{V}, I_D = -20\text{A}$	-	28	-	S
<b>Dynamic Characteristics</b>						
Input Capacitance	$C_{\text{iss}}$	$V_{\text{DS}} = -15\text{V}, V_{\text{GS}} = 0\text{V}, f = 1\text{MHz}$	-	4320	-	$\text{pF}$
Output Capacitance	$C_{\text{oss}}$		-	529	-	
Reverse Transfer Capacitance	$C_{\text{rss}}$		-	487	-	
<b>Switching Characteristics</b>						
Gate Resistance	$R_g$	$V_{\text{DS}} = 0\text{V}, V_{\text{GS}} = 0\text{V}, f = 1.0\text{MHz}$	-	4.0	-	$\Omega$
Total Gate Charge	$Q_g$	$V_{\text{GS}} = -10\text{V}, V_{\text{DS}} = -15\text{V}, I_D = -15\text{A}$	-	45	-	$\text{nC}$
Gate-Source Charge	$Q_{\text{gs}}$		-	8.5	-	
Gate-Drain Charge	$Q_{\text{gd}}$		-	12.8	-	
Turn-On Delay Time	$t_{\text{d}(\text{on})}$	$V_{\text{GS}} = -10\text{V}, V_{\text{DD}} = -15\text{V}, R_G = 2.5\Omega, I_D = -15\text{A}$	-	18.9	-	$\text{nS}$
Rise Time	$t_r$		-	15.7	-	
Turn-Off Delay Time	$t_{\text{d}(\text{off})}$		-	64.8	-	
Fall Time	$t_f$		-	36.5	-	
<b>Drain-Source Body Diode Characteristics</b>						
Diode Forward Voltage <sup>2</sup>	$V_{\text{SD}}$	$I_S = -1\text{A}, V_{\text{GS}} = 0\text{V}$	-	-	-1	V
Continuous Source Current <sup>1,5</sup>	$I_S$	$V_G = V_D = 0\text{V}$ , Force Current	-	-	-70	A

Note :

- 1.The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper.
- 2.The data tested by pulsed , pulse width  $\leq 300\mu\text{s}$  , duty cycle  $\leq 2\%$
- 3.The EAS data shows Max. rating . The test condition is  $V_{\text{DD}} = -25\text{V}, V_{\text{GS}} = -10\text{V}, L = 0.1\text{mH}, I_{\text{AS}} = -25\text{A}$
- 4.The power dissipation is limited by  $150^\circ\text{C}$  junction temperature
- 5.The data is theoretically the same as  $I_D$  and  $I_{\text{DM}}$  , in real applications , should be limited by total power dissipation.



## Typical Characteristics

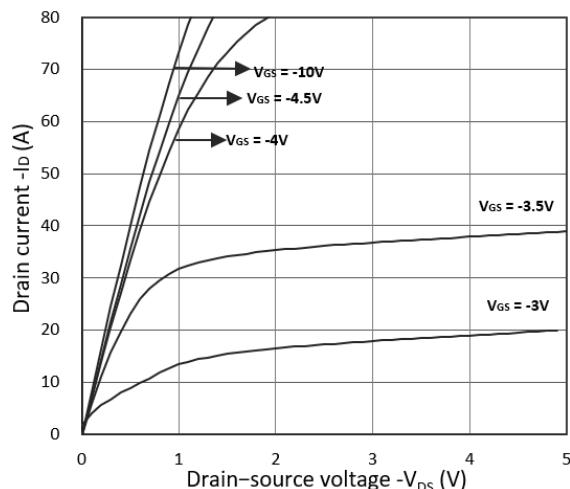


Figure 1. Output Characteristics

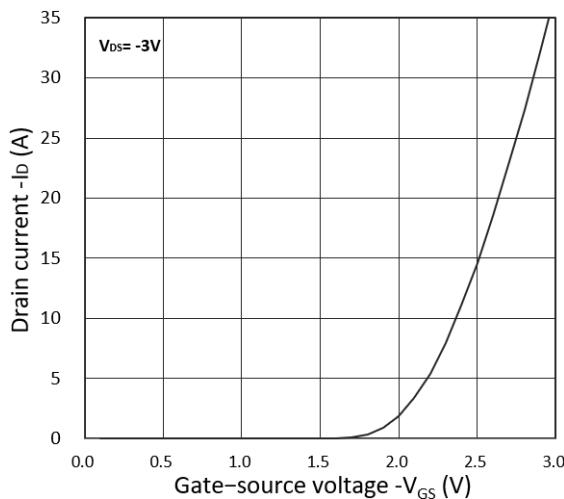


Figure 2. Transfer Characteristics

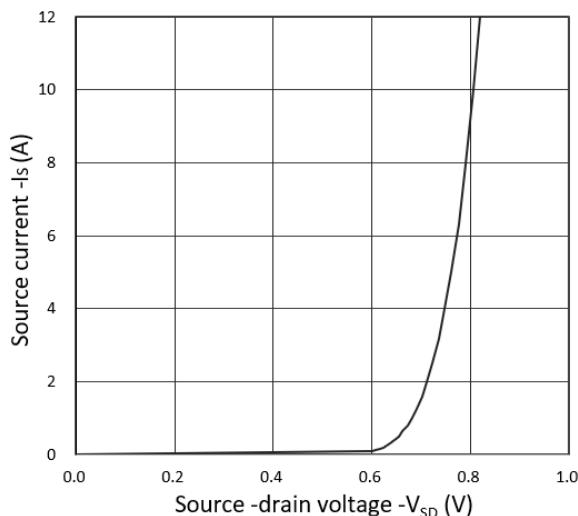


Figure 3. Forward Characteristics of Reverse

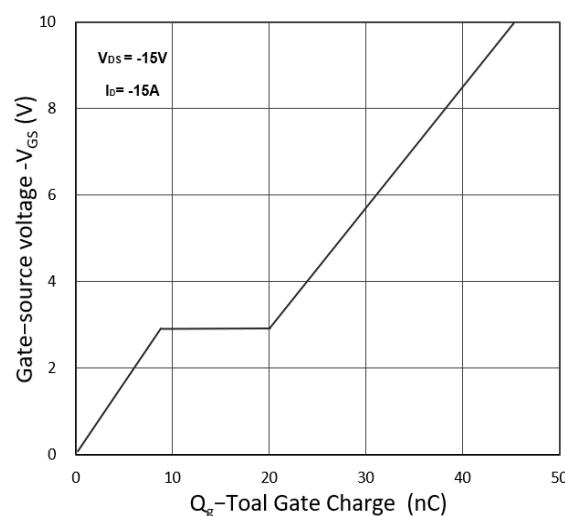


Figure 4. Gate Charge Characteristics

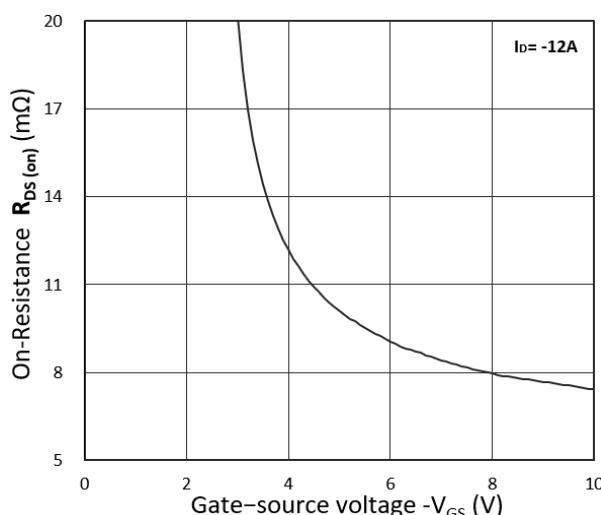


Figure 5.  $R_{DS(on)}$  vs.  $V_{GS}$

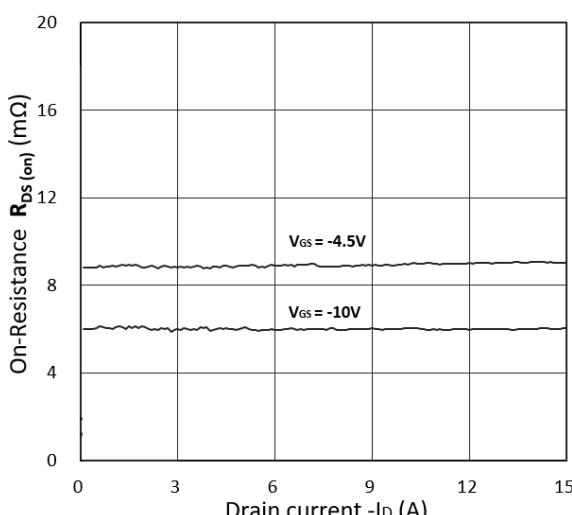


Figure 6.  $R_{DS(on)}$  vs.  $I_D$

## TM006P03NF

## P-Channel Enhancement Mosfet

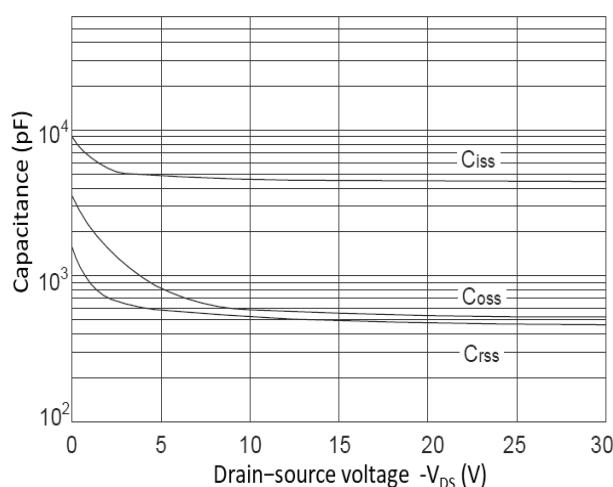


Figure 7. Capacitance Characteristics

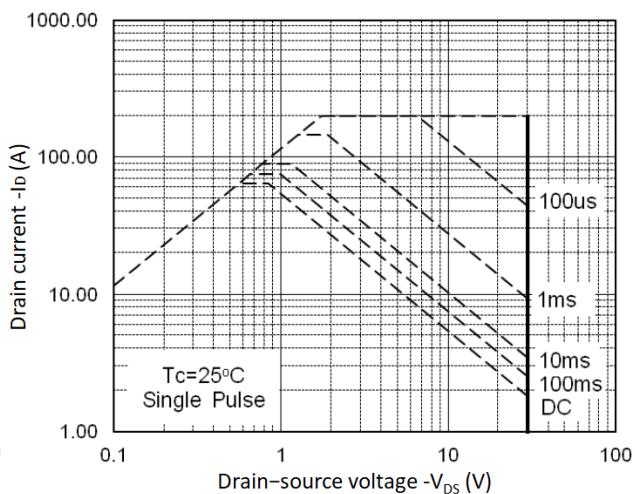


Figure 8. Safe Operating Area

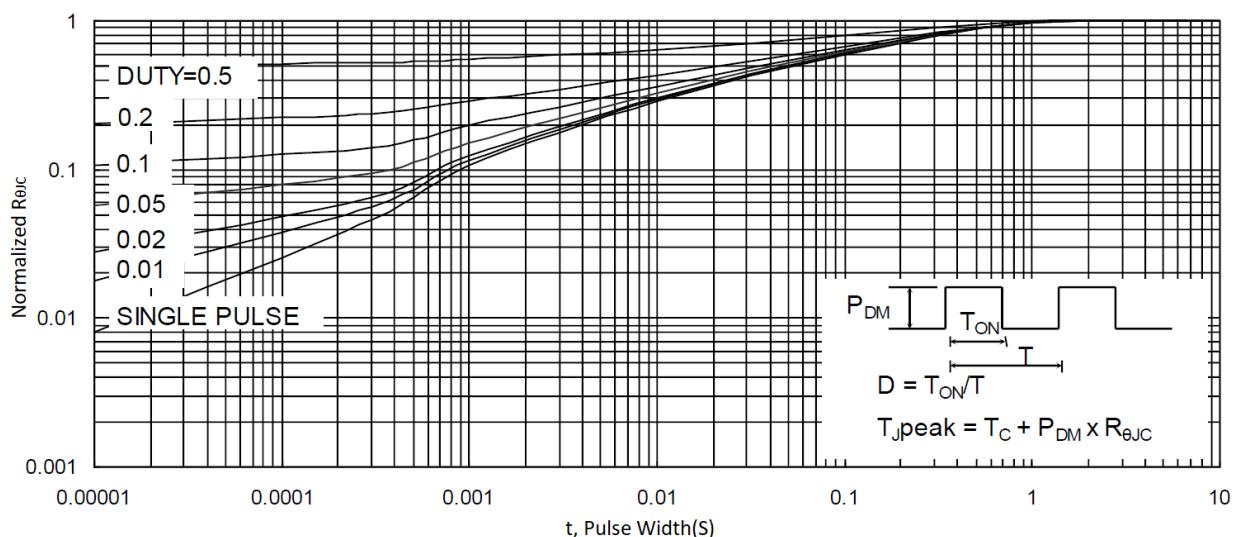


Figure 9. Normalized Maximum Transient Thermal Impedance

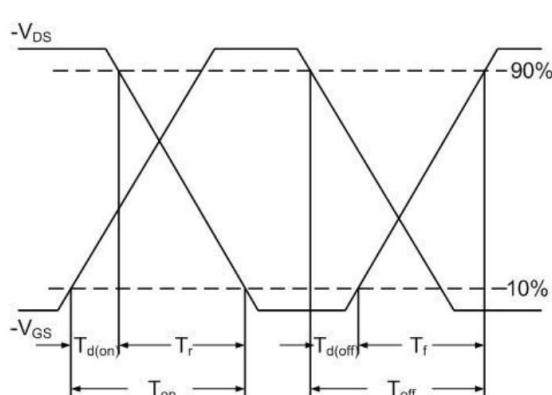


Figure 10. Switching Time Waveform

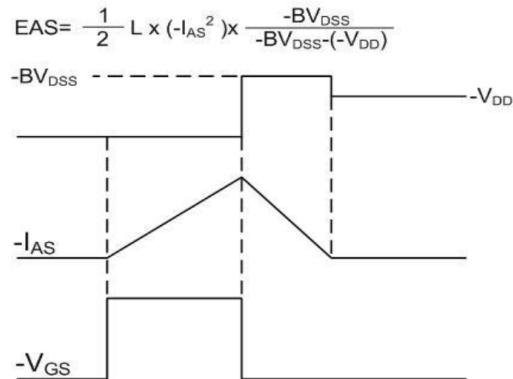


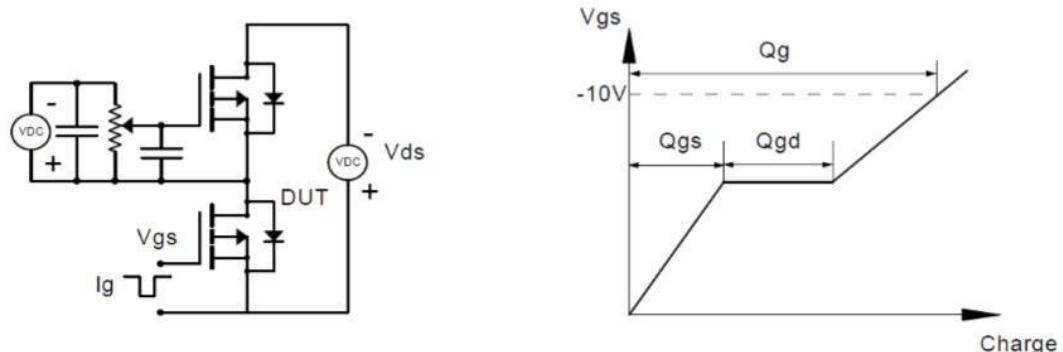
Figure 11. Unclamped Inductive Switching

Waveform

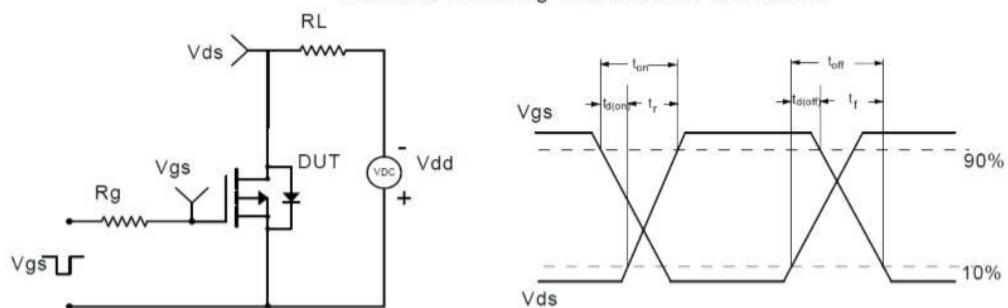


## Test Circuit

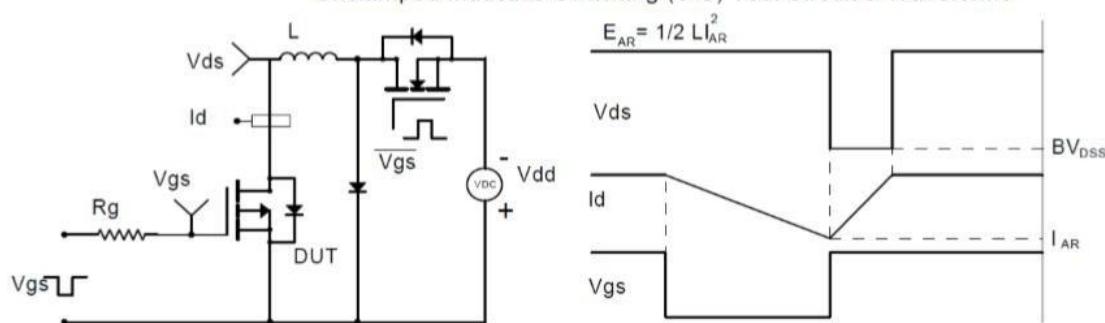
Gate Charge Test Circuit & Waveform



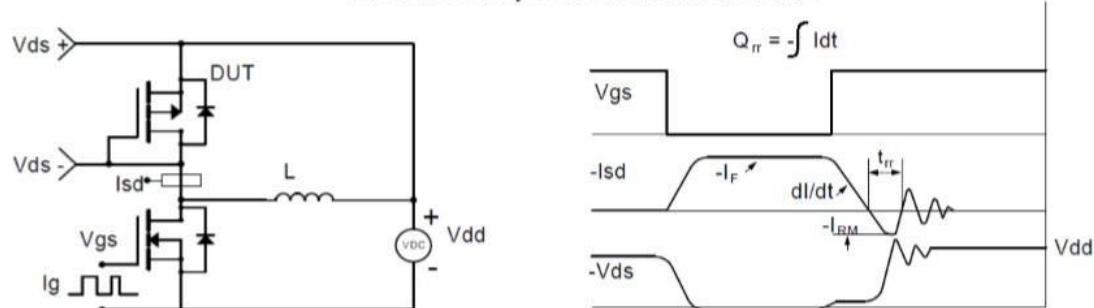
Resistive Switching Test Circuit & Waveforms



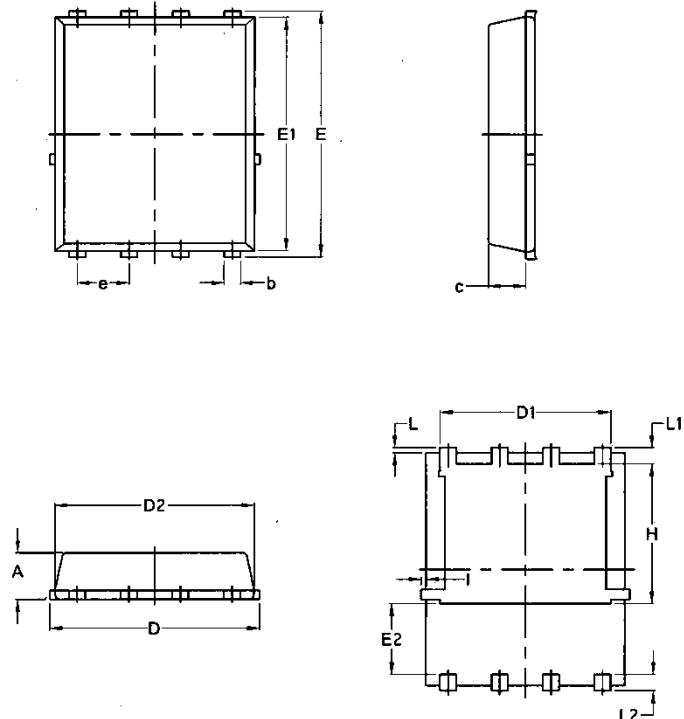
Unclamped Inductive Switching (UIS) Test Circuit & Waveforms



Diode Recovery Test Circuit & Waveforms



## Package Mechanical Data: DFN5x6-8L



Symbol	Common			
	mm		Inch	
	Min	Max	Min	Max
A	1.03	1.17	0.0406	0.0461
b	0.34	0.48	0.0134	0.0189
c	0.824	0.0970	0.0324	0.082
D	4.80	5.40	0.1890	0.2126
D1	4.11	4.31	0.1618	0.1697
D2	4.80	5.00	0.1890	0.1969
E	5.95	6.15	0.2343	0.2421
E1	5.65	5.85	0.2224	0.2303
E2	1.60	/	0.0630	/
e	1.27 BSC		0.05 BSC	
L	0.05	0.25	0.0020	0.0098
L1	0.38	0.50	0.0150	0.0197
L2	0.38	0.50	0.0150	0.0197
H	3.30	3.50	0.1299	0.1378
I	/	0.18	/	0.0070